

SOT579-1

plastic ball grid array package; 272 balls; body 27 x 27 x 1.55 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA272
Package type industry code	BGA272
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	28-9-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	[tbd]	-	2.3	2.3	mm
A ₂	package height	1.45	-	1.55	1.6	mm
n ₂	actual quantity of termination	-	-	272	-	



2. Package outline

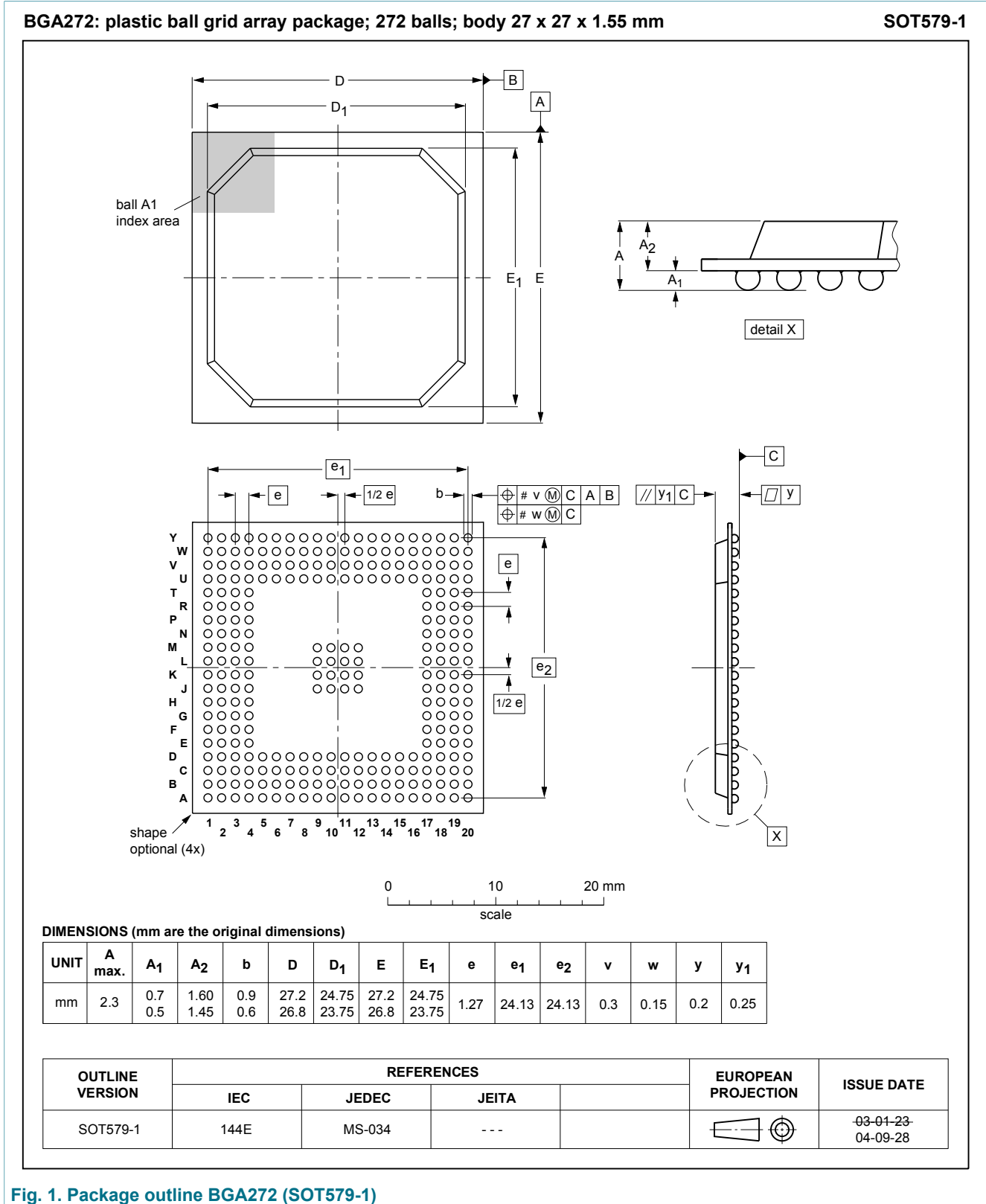


Fig. 1. Package outline BGA272 (SOT579-1)

3. Soldering

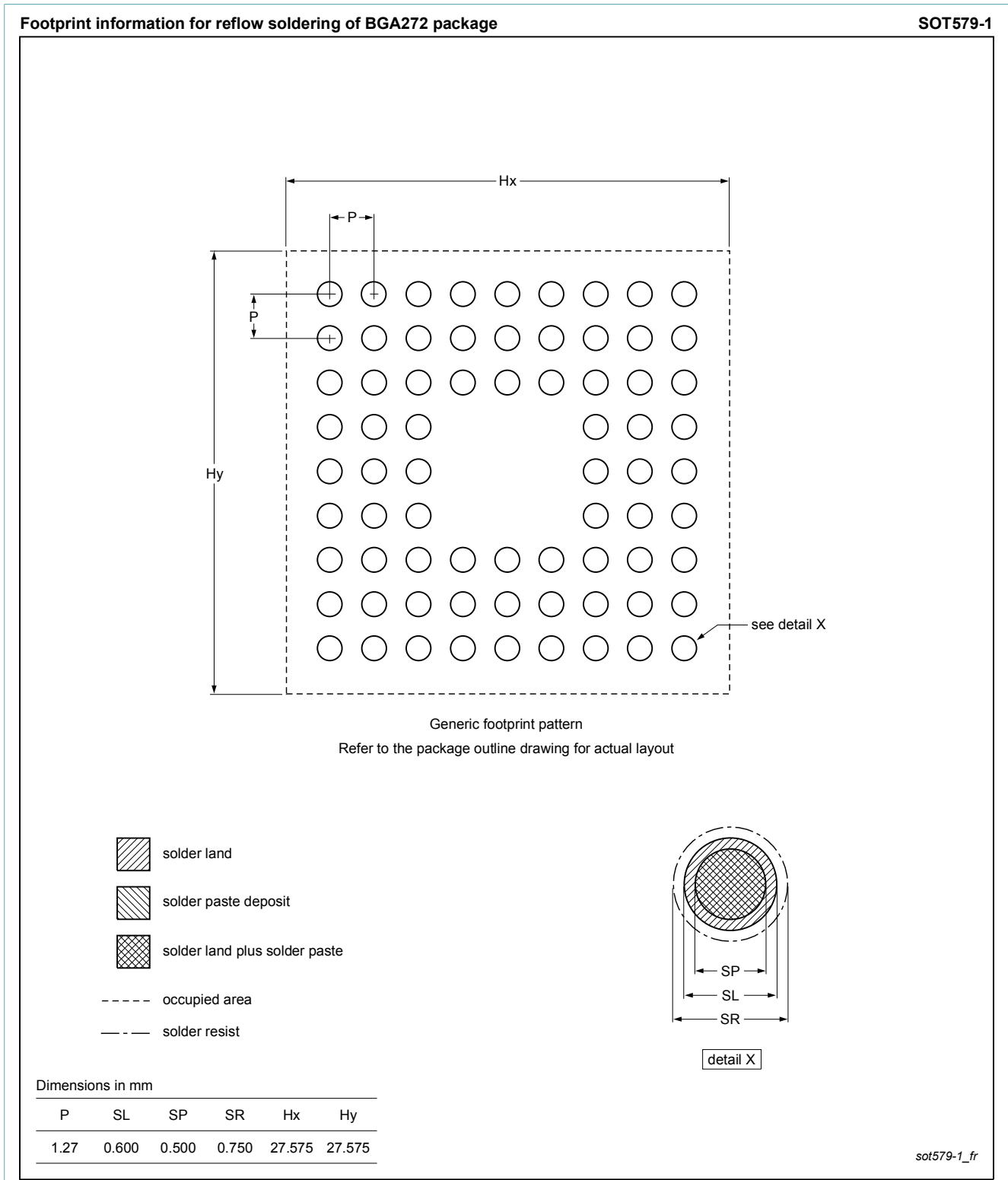


Fig. 2. Reflow soldering footprint for BGA272 (SOT579-1)

4. Legal information

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Date of release: 8 February 2016
